EAST - [10.751316 - Parasitic Test Method.wsp:1]

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	Hits	Search Text	DBs	Time Stamp
1	551	semiconductor and test$3 and (parasitic with diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 12:10
2	19	(semiconductor and test$3 and (parasitic with diode)) and (257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.) not ((semiconductor and test$3 and heat$3 and sensor and parasitic) and (257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/03 15:38
3	85	semiconductor and test$3 and (parasitic with diode) and parasitic.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 12:10
4	10769	257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 12:40
5	5	(semiconductor and test$3 and (parasitic with diode) and parasitic.ab.) and (257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 12:11
6	1	semiconductor and test$3 and heat$3 and sensor and parasitic and (buried with (heating adj element))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/04 15:20
7	1	"10/200934"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 12:23
8	6	("5195827" "5309090" "5280237").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 12:40
9	11695	257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 12:40
10	956	parasitic same temperature same substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 12:41
11	16	(257/467,48,797,E21.521.ccls. 73/777.ccls. 324/765-769,158,252.ccls. 374/178,183-185.ccls. D10/77.ccls. 438/18.ccls.) and (parasitic same temperature same substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 14:02
12	5	("4356379" "5414370").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/14 14:02

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